



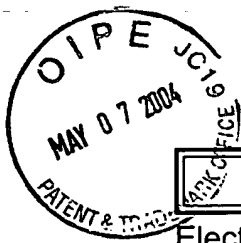
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 60605
Application ID: 10763859
Title of Invention: SEMICONDUCTOR PACKAGE
HAVING REDUCED THICKNESS
First Named Inventor: TAE LEE
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-01-23
Effective Receipt Date: 2004-05-07
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 8528
Attorney Docket Number: AMKOR053G




Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
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<p>Application Number: 10/763859 </p> <p>Date: 2004-01-23</p> <p>First Named Applicant: TAE HEON LEE</p> <p>Confirmation Number: 8528</p> <p>Attorney Docket Number: AMKOR053G</p>								
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	33	6583503	2003-06-24	Akram et al.
	34	6667546	2003-12-23	Huang et al.

Signature

Examiner Name	Date